

METHODS FOR ASSEMBLY AND PACKAGING OF FLIP CHIP CONFIGURED DICE WITH INTERPOSER

Inventors: Teck Kheng Lee

Filed: April 22, 2004

Attorney Docket No. 4974.1US

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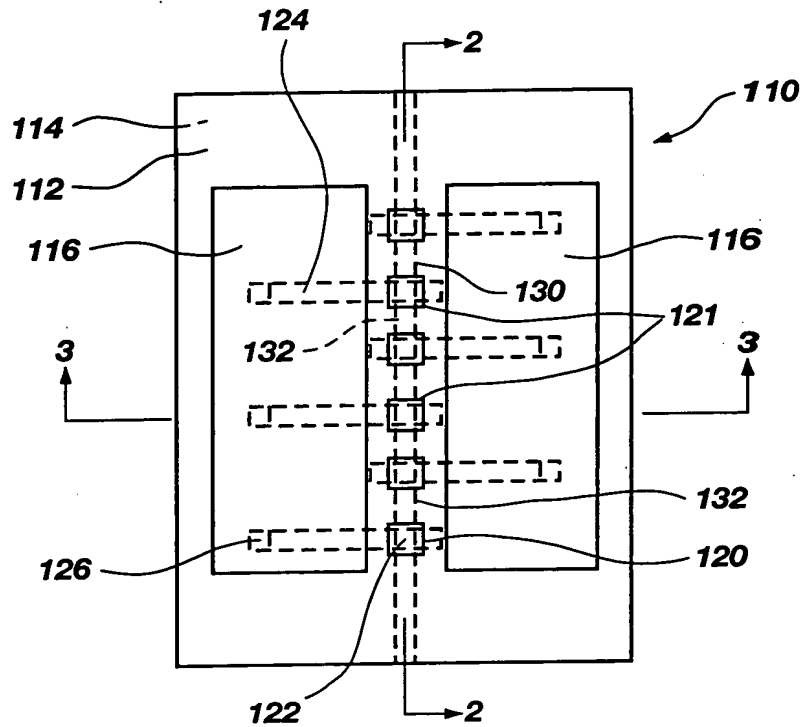


Fig. 1

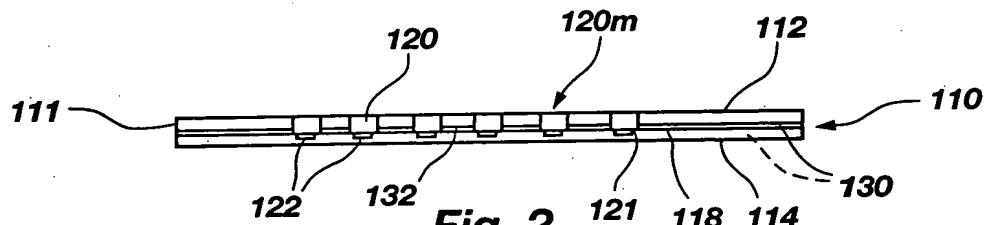


Fig. 2

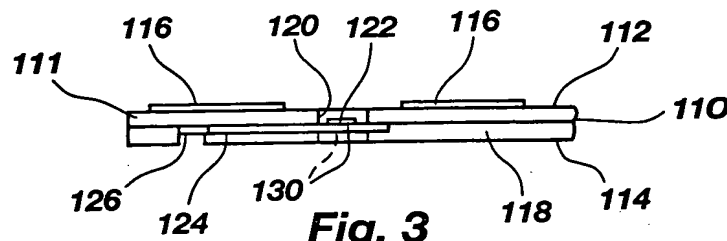


Fig. 3

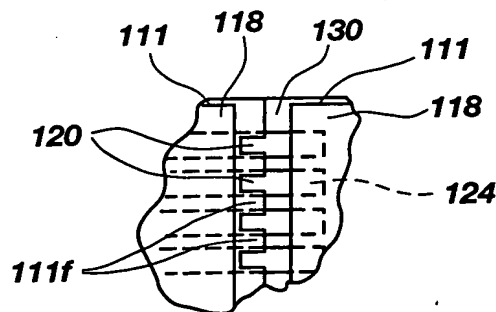


Fig. 1A

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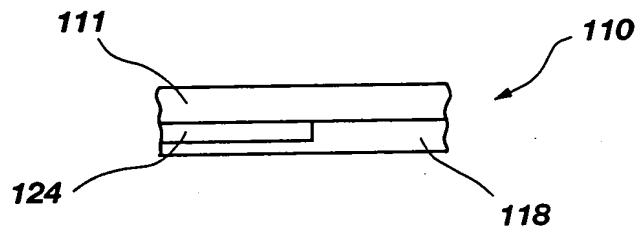


Fig. 4A

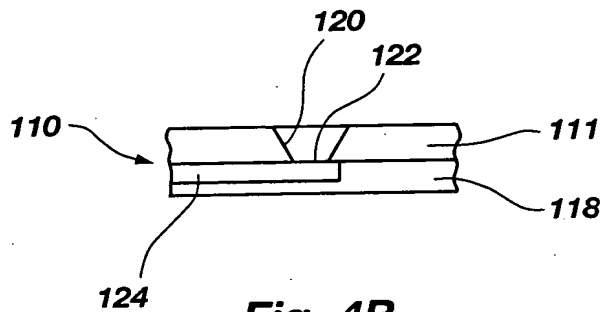


Fig. 4B

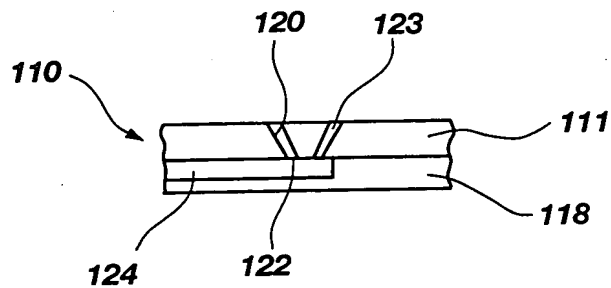


Fig. 4C

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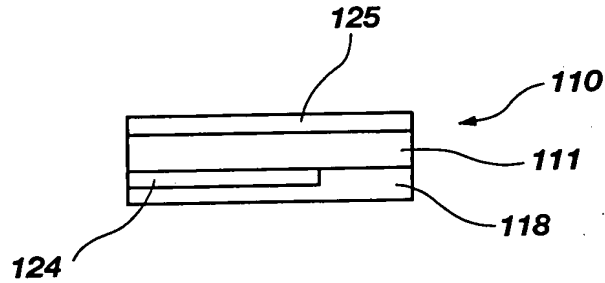


Fig. 5A

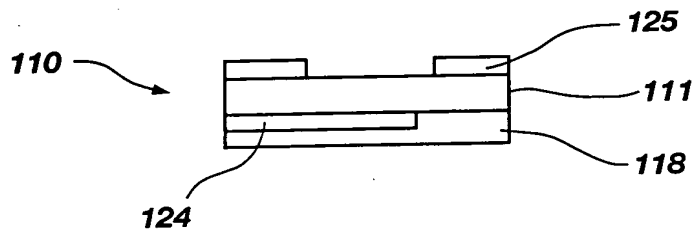


Fig. 5B

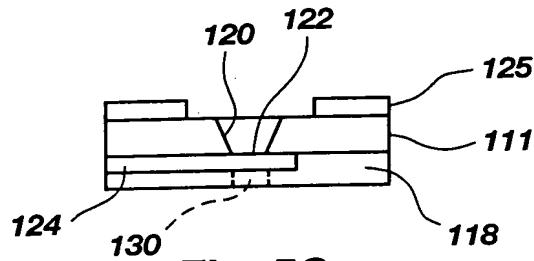


Fig. 5C

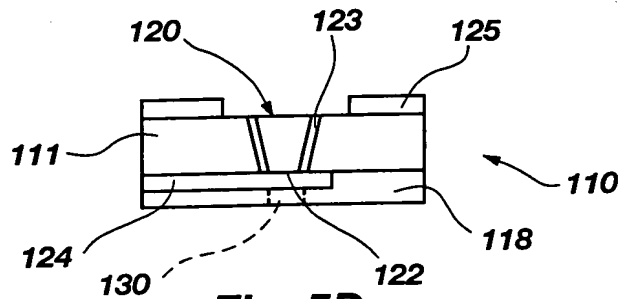


Fig. 5D

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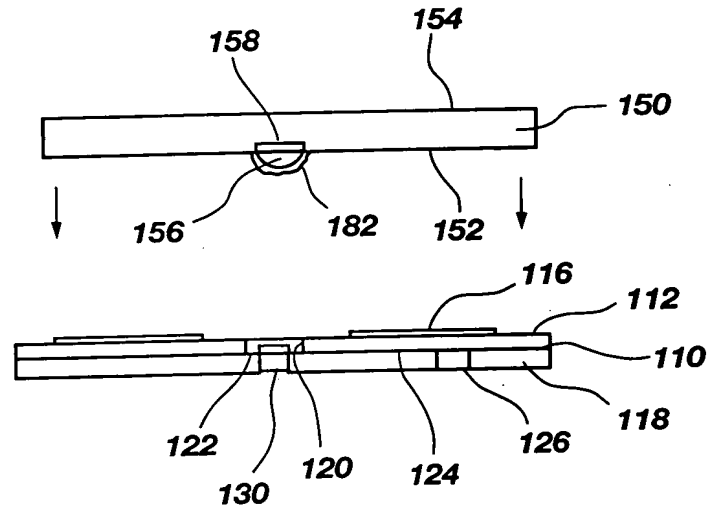


Fig. 7A

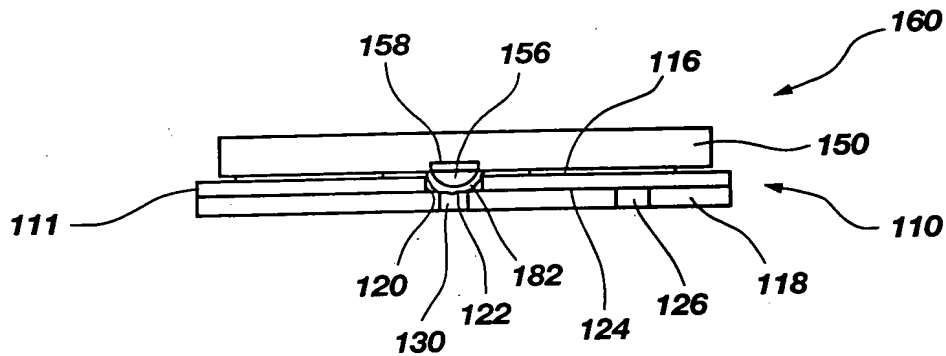


Fig. 7B

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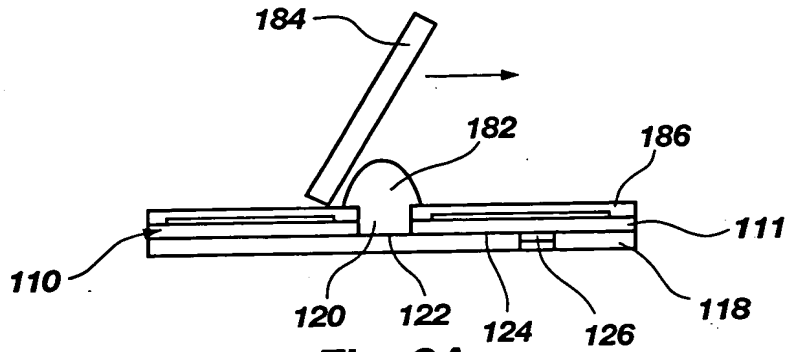


Fig. 8A

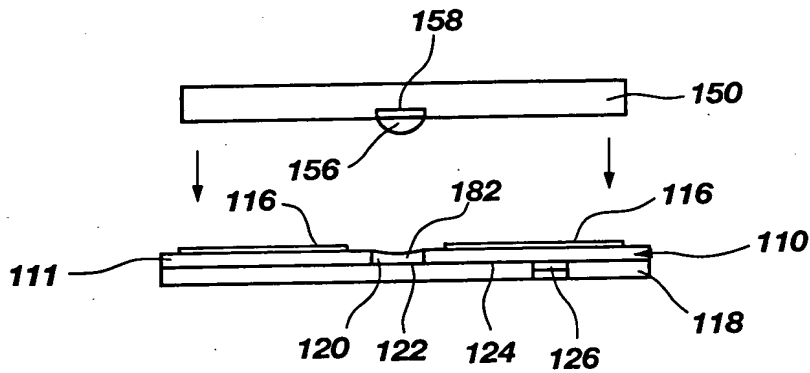


Fig. 8B

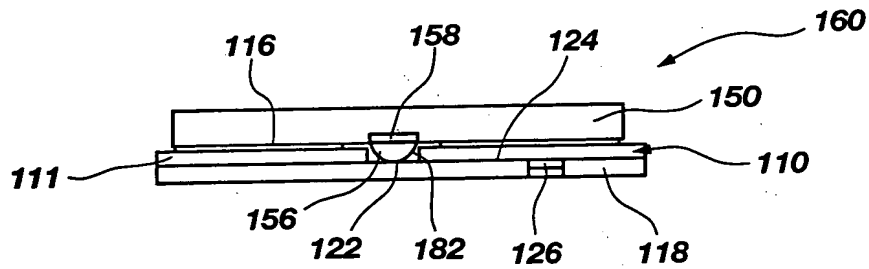


Fig. 8C

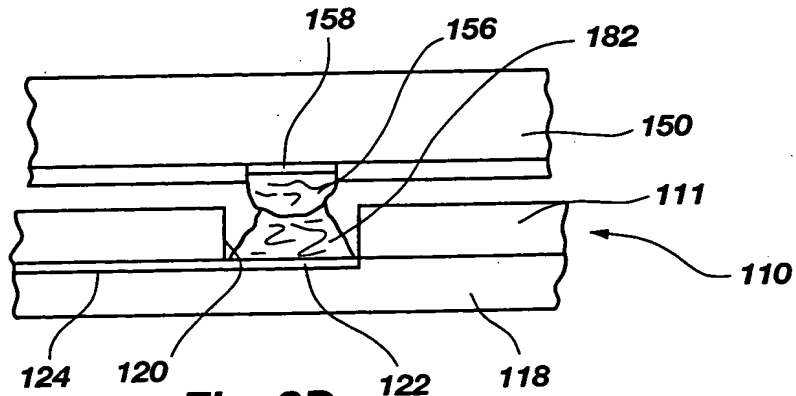


Fig. 8D

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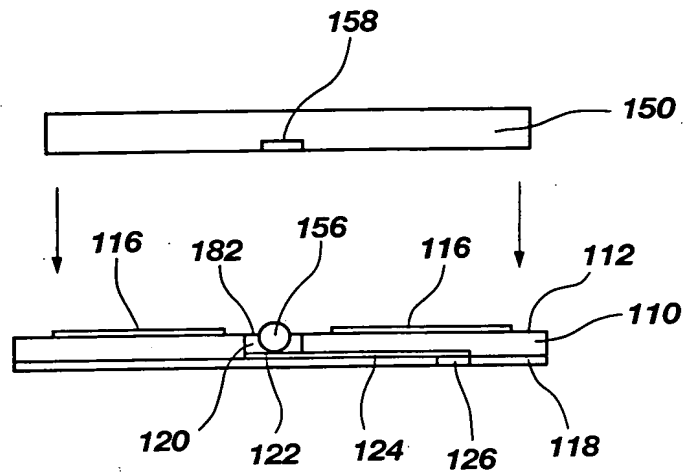


Fig. 9A

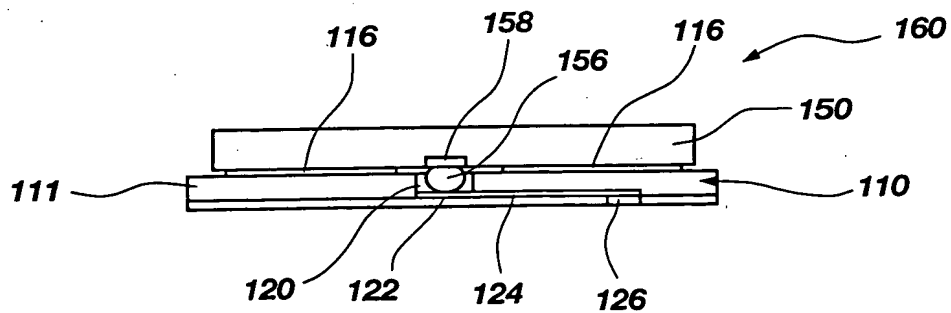


Fig. 9B

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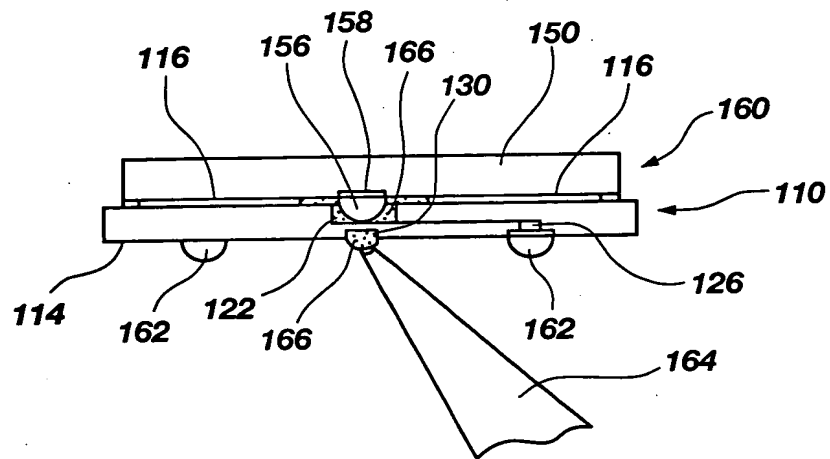


Fig. 10

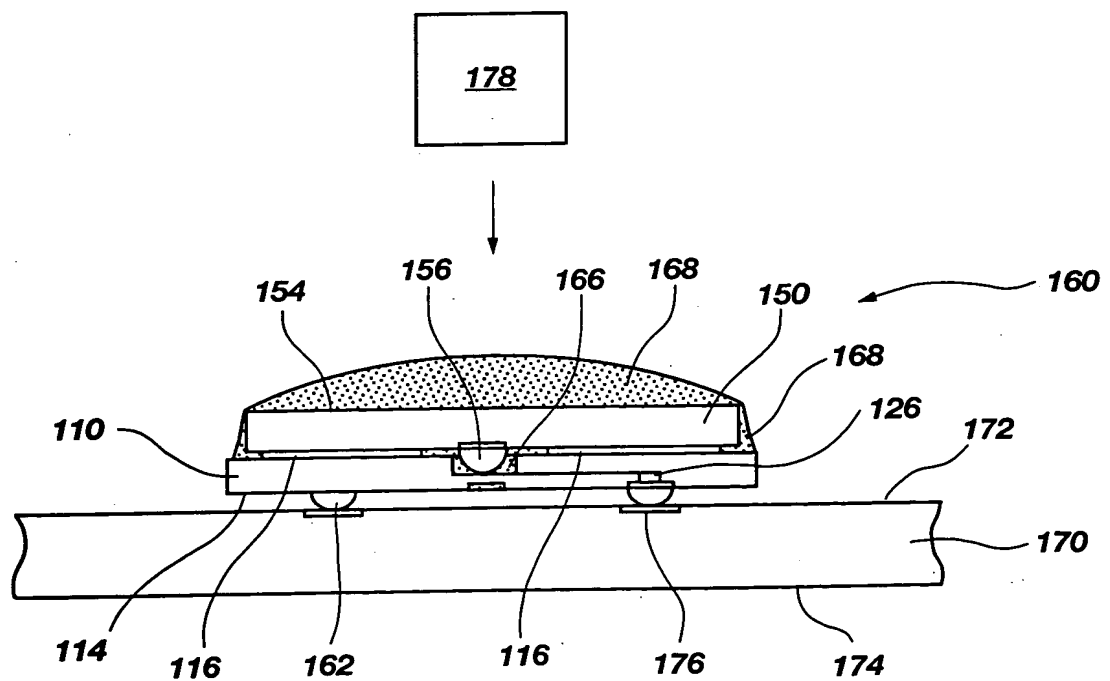


Fig. 11

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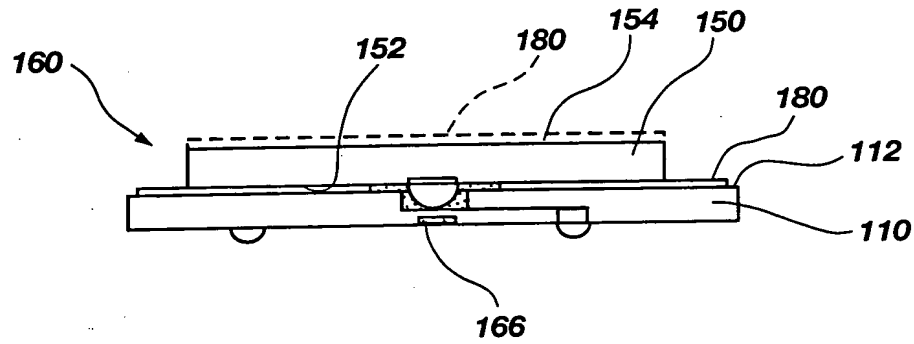


Fig. 12

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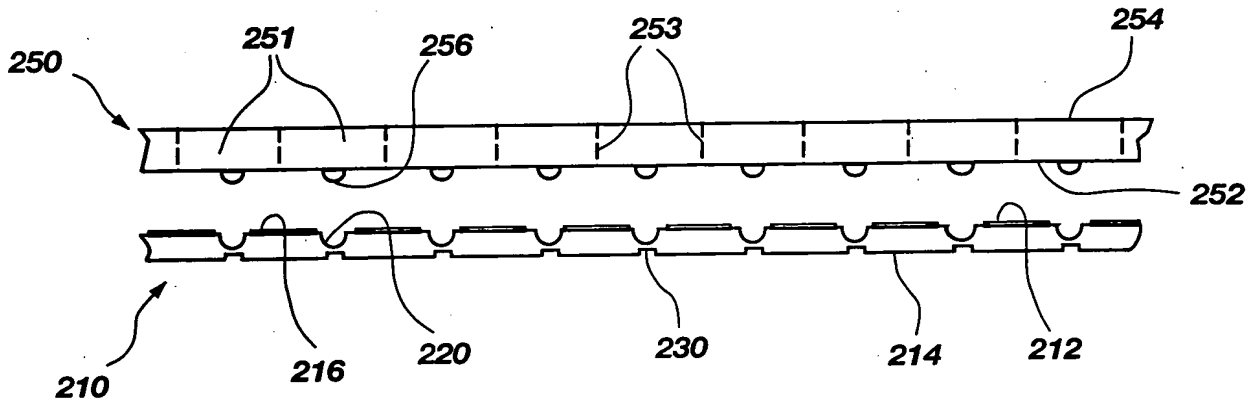


Fig. 13A

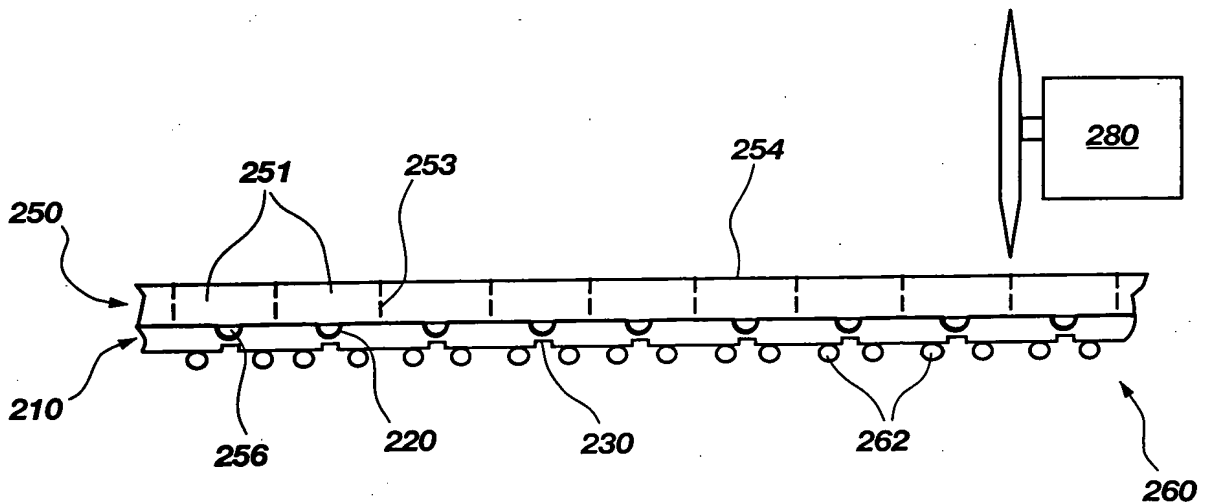


Fig. 13B

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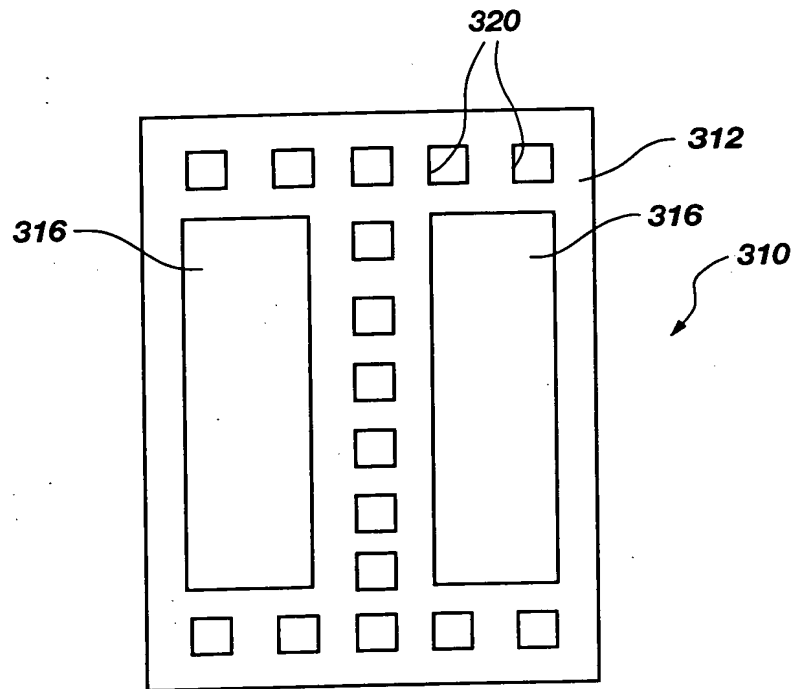


Fig. 14

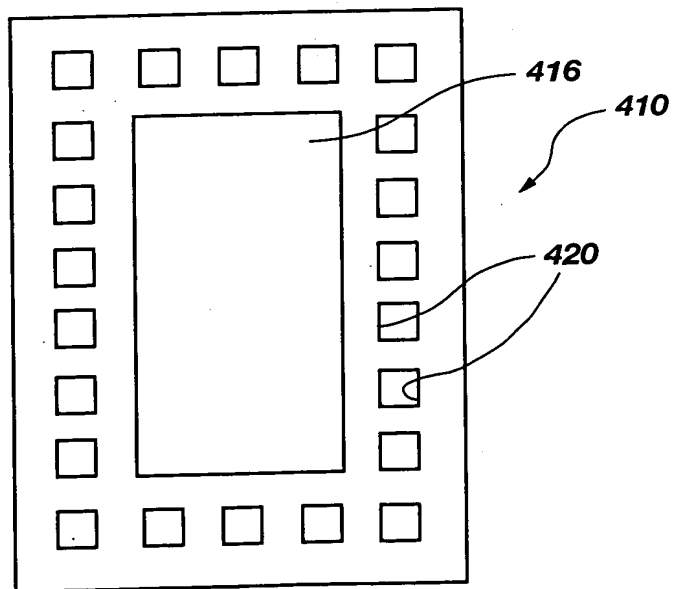


Fig. 15



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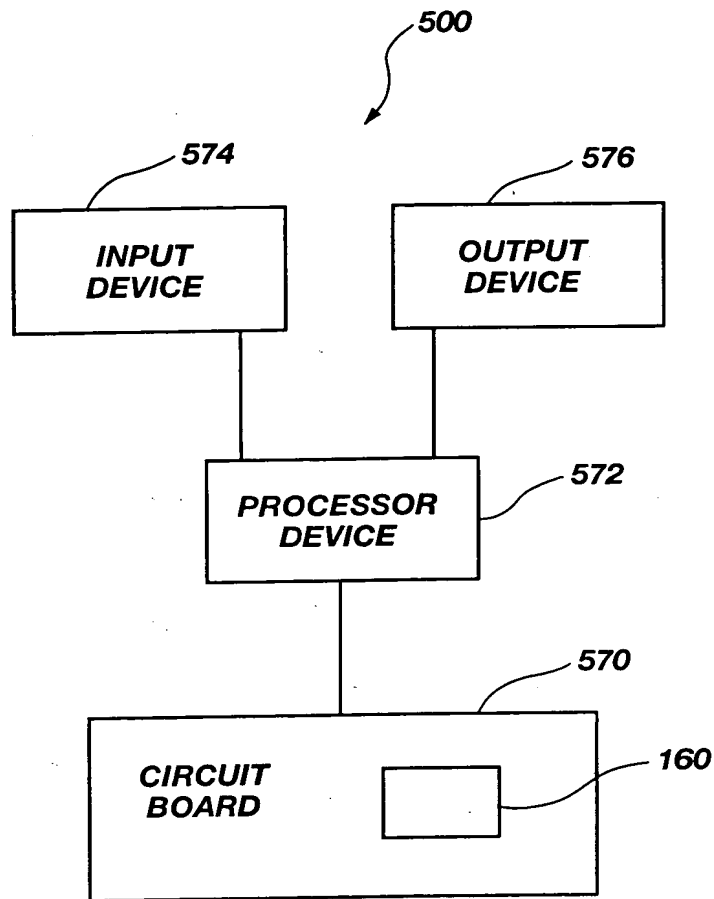


Fig. 17